

## RUTRONIK TechTalk meets **Gate Driver**

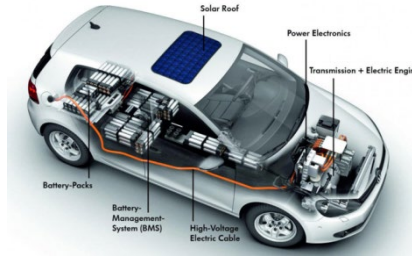
### DC/DCs for isolated gate drivers for e-mobility applications

Steve Roberts | Innovation Manager

RECOM Engineering GmbH & Co. KG



# What do all these applications have in **RECOM** common?-they all use high frequency switchers



# Advantages of Fast Switching

- Improved power density

(smaller components)

- Higher efficiency

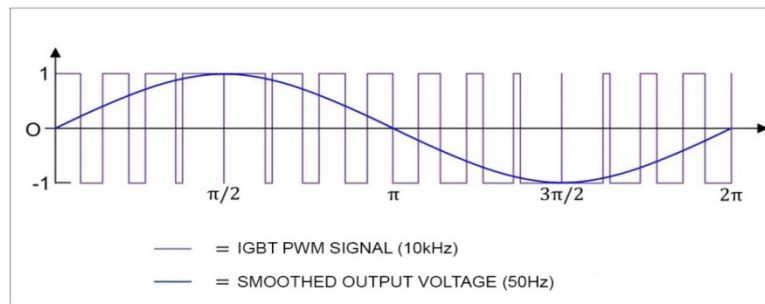
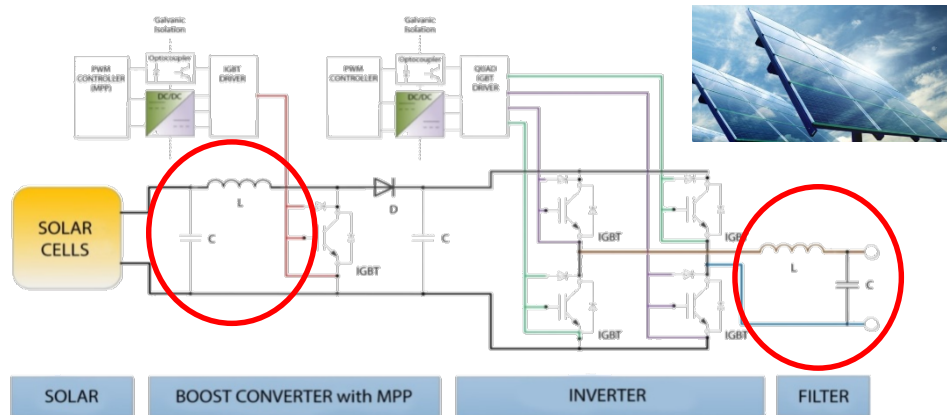
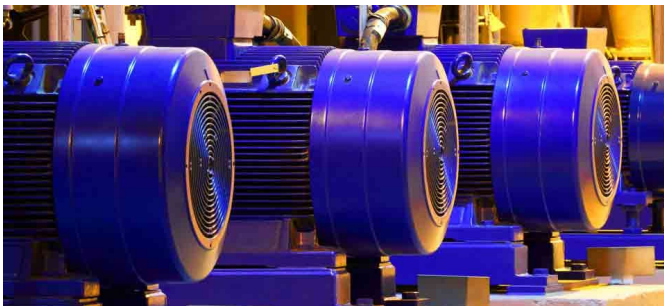
(over a wider input voltage range)

- More precise control

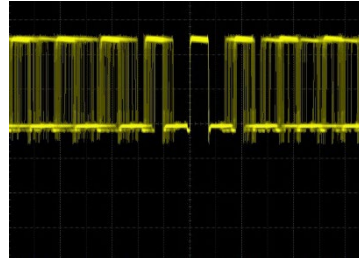
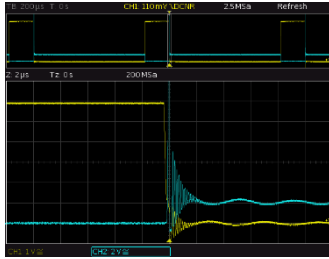
(faster response)

- Avoid AM Radio Band

(535-1605kHz)



# Disadvantages of Fast Switching



- Higher peak voltages (EMI problems?)
- High  $dv/dt$  stress on components (Lifetime?)
- High  $di/dt$  makes layout critical (Hidden costs?)
- Switching reliability and stability (1st. Pulse?)  
(Analogy: racehorse vs carthorse)



# Power/Switching Freq.

## Comparison

Type	$f_{max}$
Si	100kHz @ 100kW
SiC	1MHz @ 100kW
GaN	3MHz @ 3kW

$$f_{max} = \frac{1}{t_d + t_r + t_s + t_f}$$

Switch on:

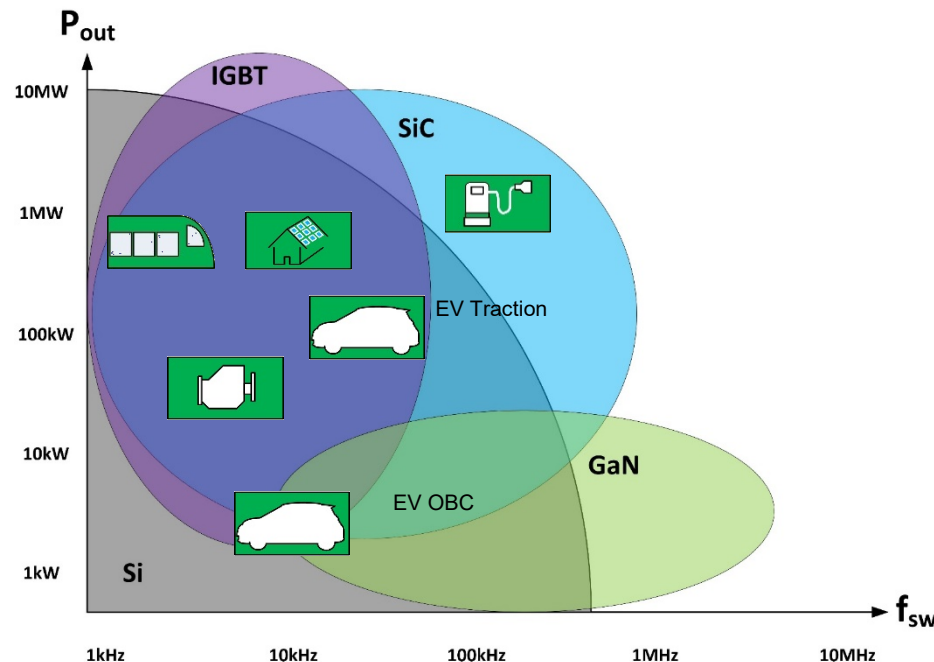
Delay time ( $t_d$ ) - how long it takes to get out of cutoff

Rise time ( $t_r$ ) - transition from cutoff to saturation

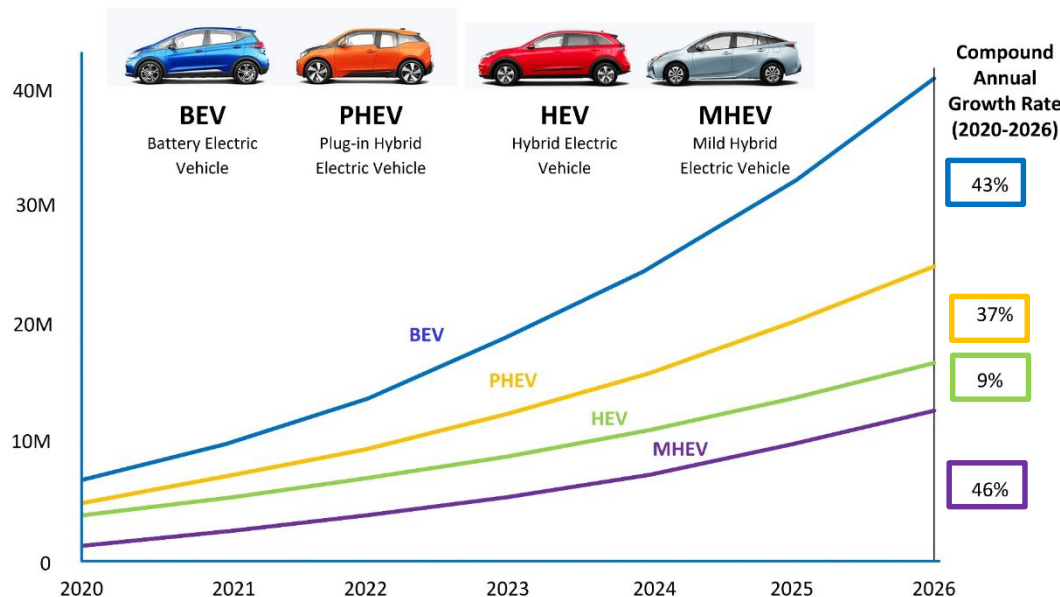
Switch off:

Storage time ( $t_s$ ) - how long to get out of saturation

Fall time ( $t_f$ ) - transition from saturation to cutoff



# Hybrid/Battery Electric Vehicles



2nd. Gen. BEV,  
PHEV, HEV  
„800V“ (650 – 920V)

1200V  
Transistors

1st. Gen. BEV,  
PHEV, HEV  
„400V“ (200-450V)

900V  
Transistors

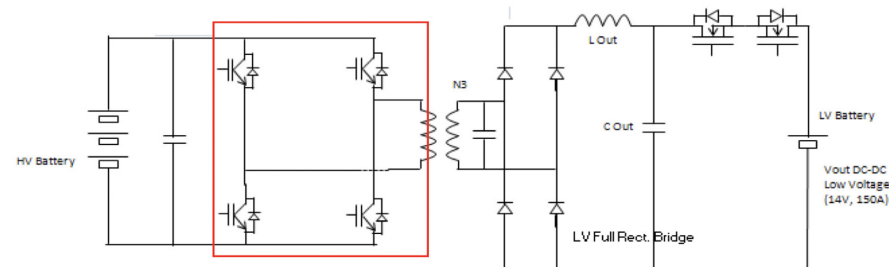
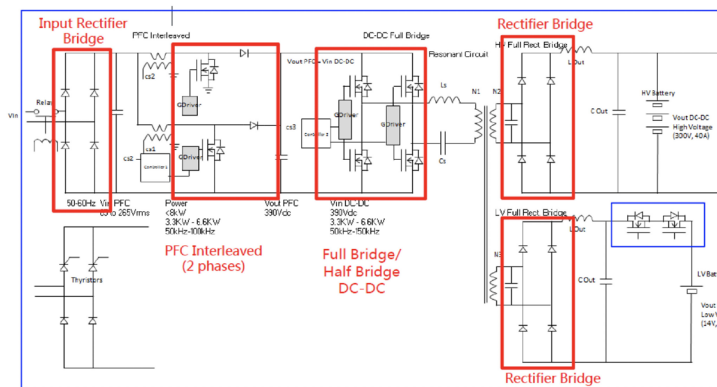
MHEV  
„48V“ (20-60V)

100V  
Transistors

# E-mobility Applications

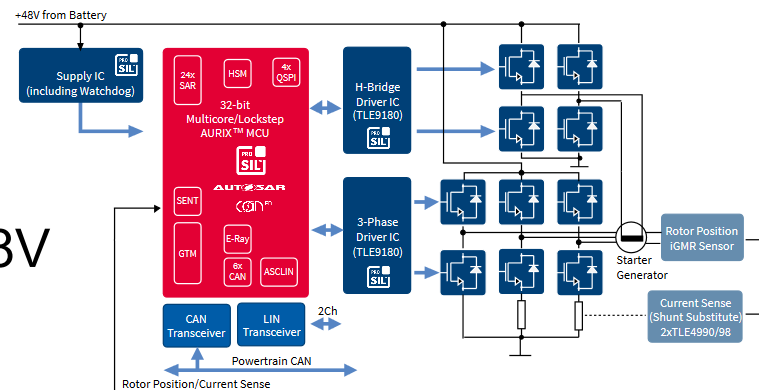


## On-Board DC/DC

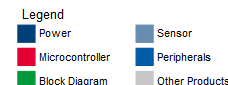


## On-Board Charger

## Microhybrid 48V Powertrain

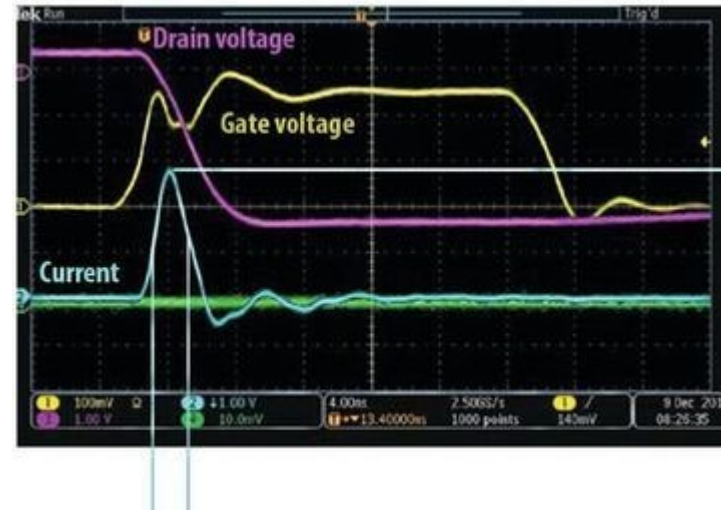
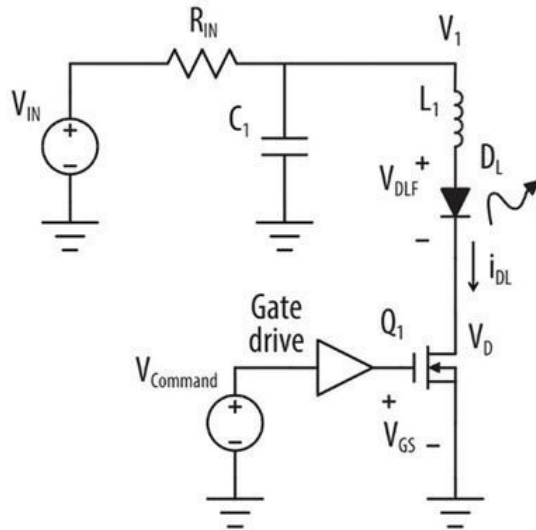


<https://rutronik-tec.com/rutronik-automotive-drive-train/infineon-powertrain-48v-application-microhybrid/>



# E-mobility Applications

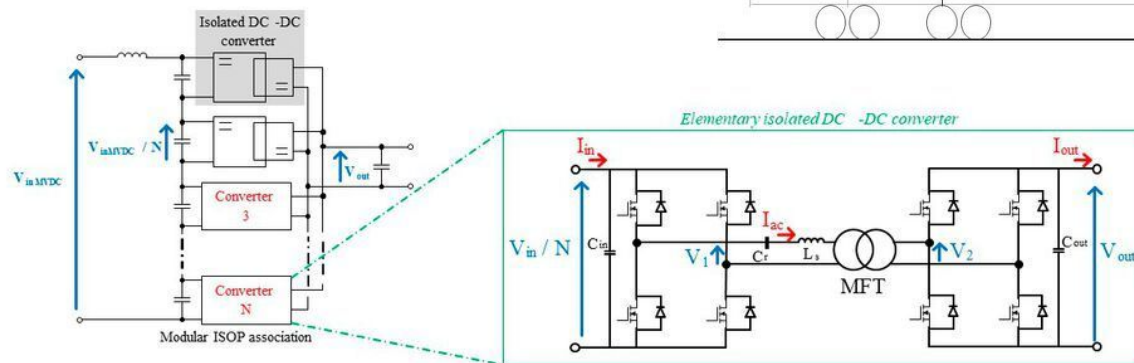
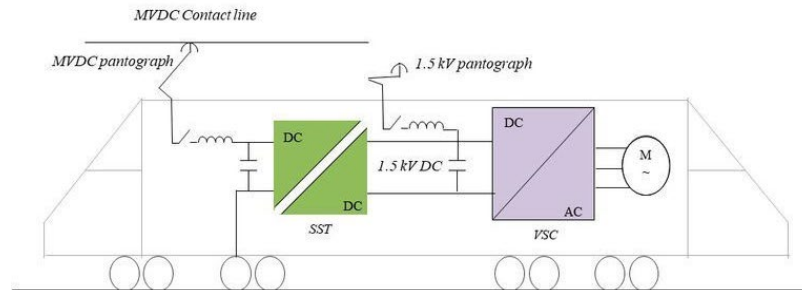
## LIDAR (capacitive discharge laser driver)



60A peak

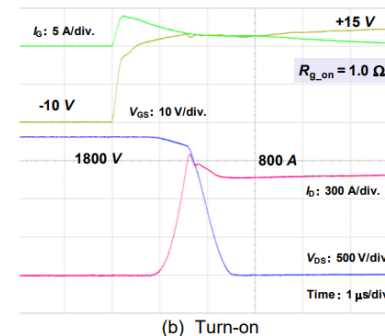
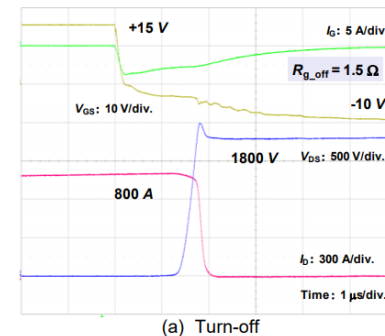
4ns pulse width

# Railway „Solid-State Transformer“



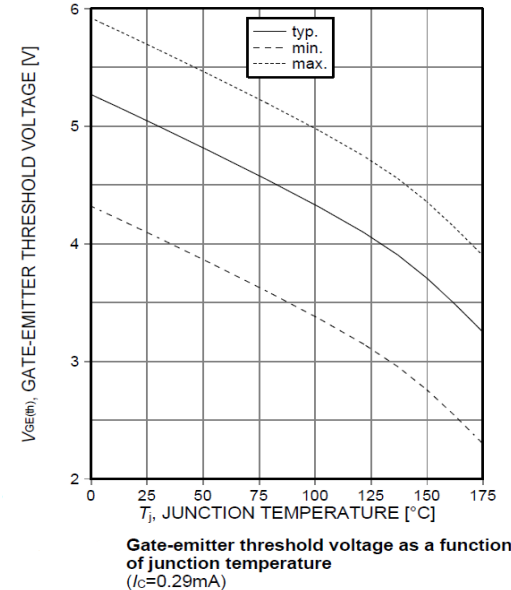
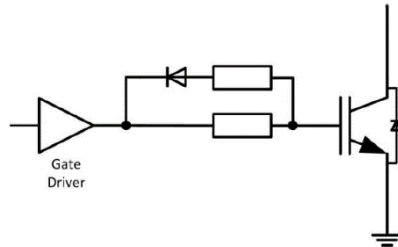
# Design Considerations for High Frequency Switching

- Design Issues for the Gate Driver Circuit
- Which WBG Transistor?
- Isolated Power for the Gate Driver



# Design Considerations for High Frequency Switching: Gate Threshold Voltage

The gate threshold voltage,  $V_{TH}$ , is typically 2-4 volts above the emitter/source terminal voltage, with some variation between components and over temperature:



If there is no gate drive, the transistor is clearly off, but many datasheets recommend a negative gate drive „for safety“. Why?

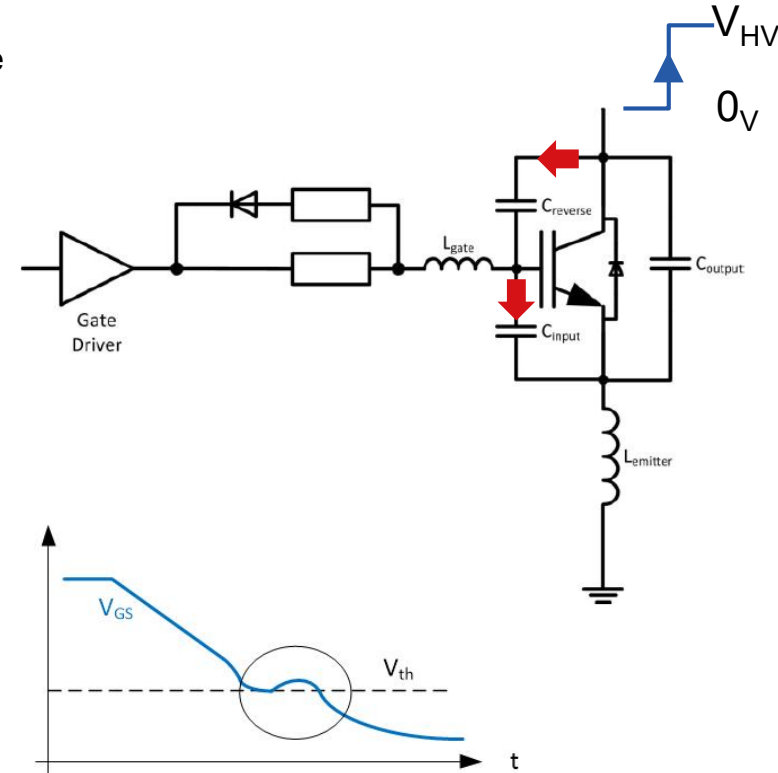
## Why Negative Gate Drive?

False turn-on via gate capacitance ( $C_{\text{reverse}}$  or  $C_{\text{Miller}}$ )

High turn-off  $dv/dt$  causes current to flow through  $C_{\text{reverse}}$  which charges up  $C_{\text{input}}$  forcing  $V_{\text{gate}}$  to rise.

Worst case: the transistor turns back on again!

RECOM



# Why Negative Gate Drive?

False turn-on via „ground bounce“ across

$L_{\text{emitter}}$

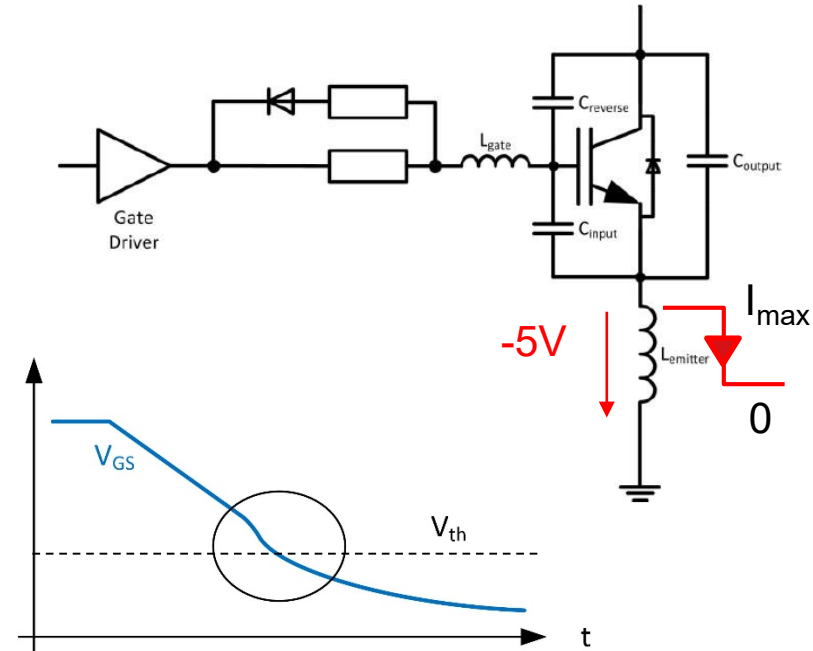
High  $di/dt$  induces a voltage across any layout inductances:  $-V = L * di/dt$

e.g. If  $L_{\text{emitter}} = 5 \text{ nH}$

(inductance of 5mm PCB track) then:

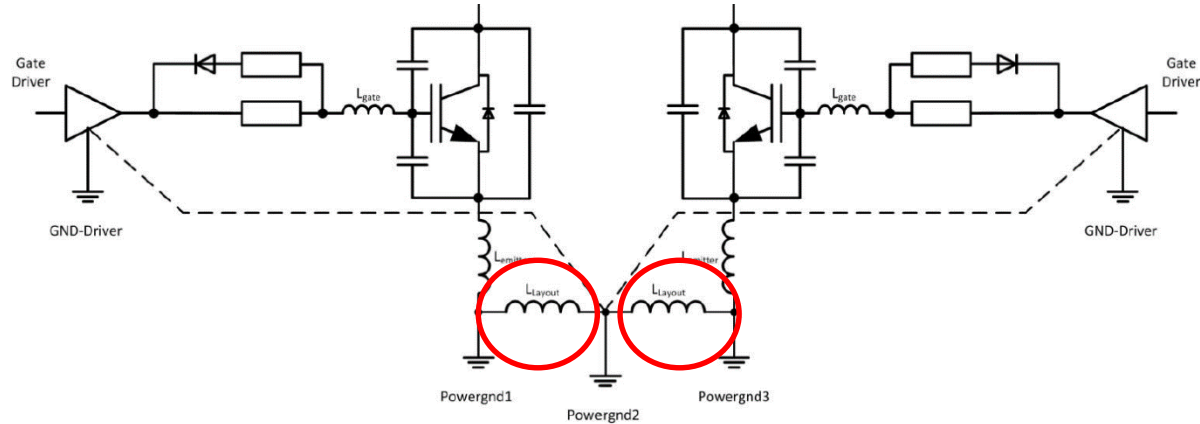
$$-V = 5 \text{ nH} * 1000 \text{ A}/\mu\text{s} = - \underline{5 \text{ V}}$$

Worst case: the transistor turns back on again!



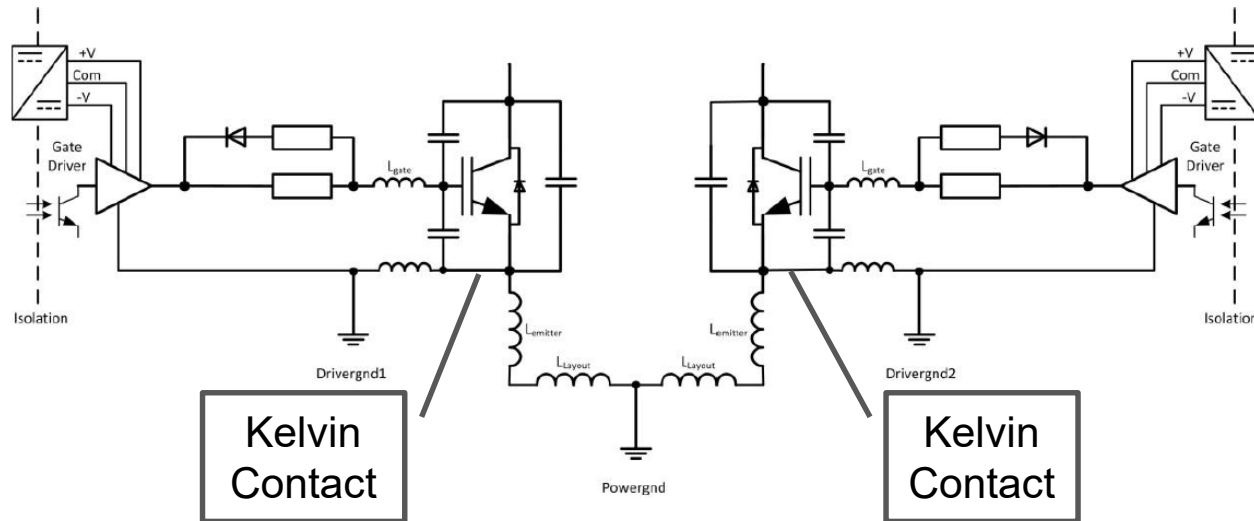
# Layout Parasitic Inductance

Any imbalance in the layout parasitics can cause an imbalance in the switching behaviours of each leg :



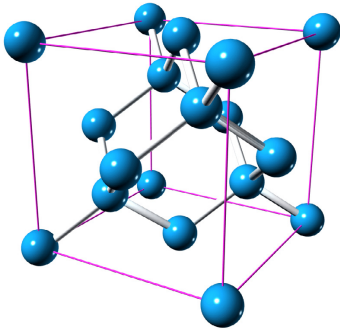
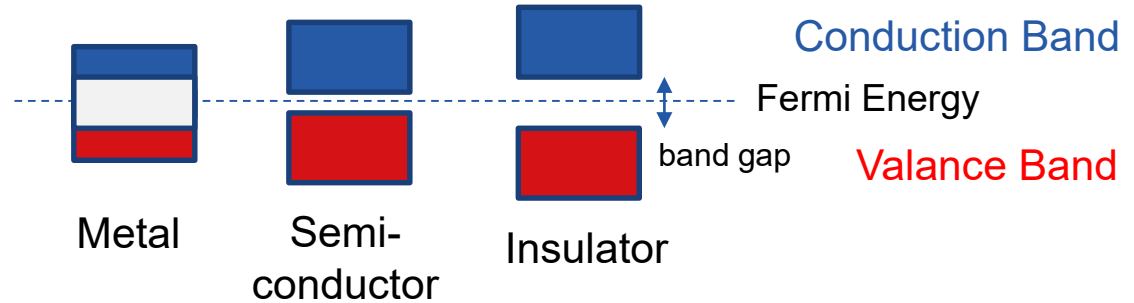
# Layout Parasitic Inductance

One way of eliminating the influence of layout parasitics is to use isolated gate drivers, isolated power supplies and Kelvin (SS) contacts (note: low side, so functional isolation is sufficient!)

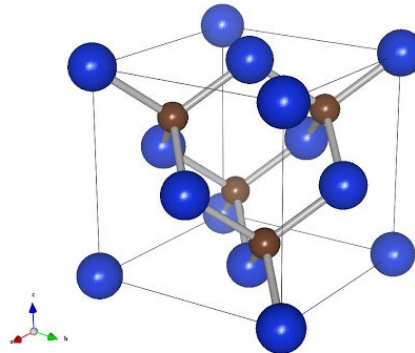


# Wide Band Gap Transistors

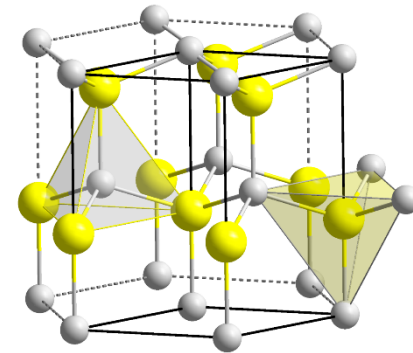
- Silicon Carbide (SiC)
- Gallium Nitride (GaN)



Si



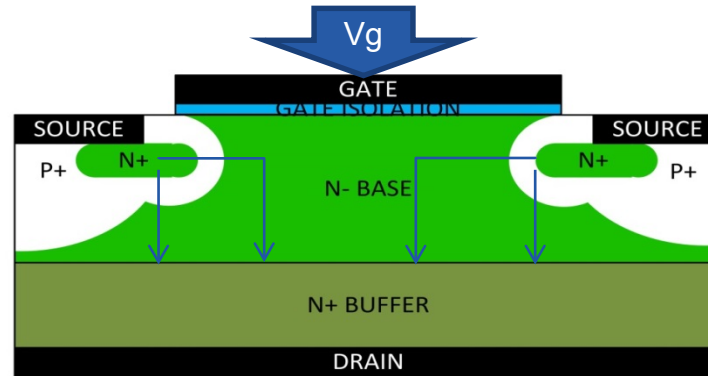
SiC



GaN

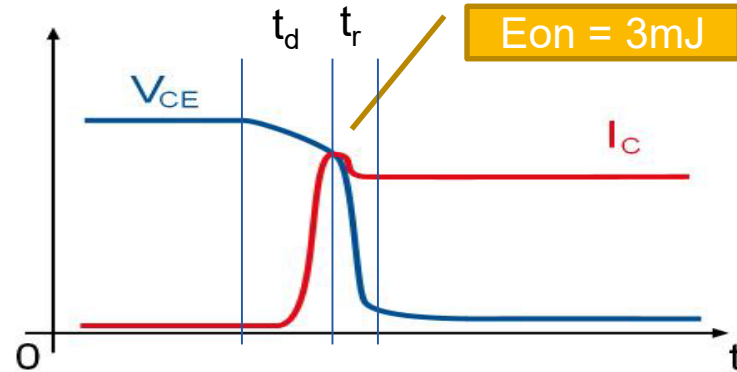
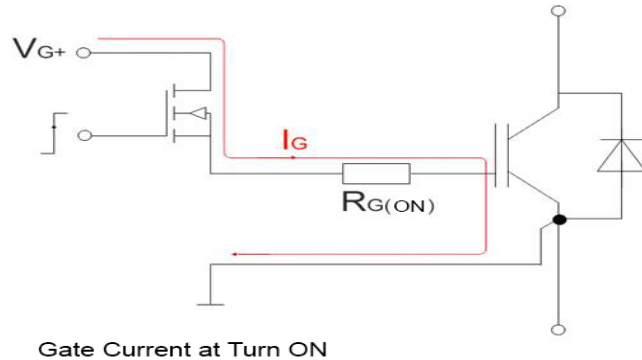
Source: Wikipedia

# Si/SiC Construction



- SiC 10x higher dielectric breakdown than Si (thinner layers = lower resistance)
- SiC 3x better thermal conductivity as Si (higher power rating)

## Turn On Gate Drive: SiC



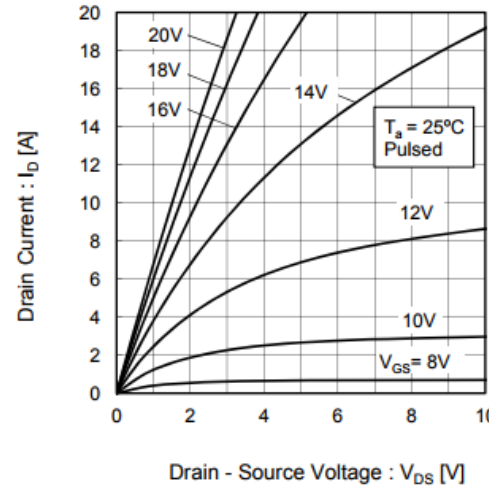
- SiC has significantly lower switching power dissipation than Si
- Switching speed mainly determined by  $R_{G(ON)}$  gate resistor

## +Ve Turn On Gate Drive: SiC

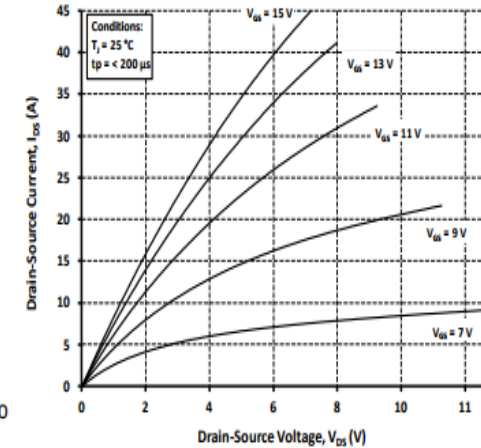


$+V_{GS} \text{ max} = +20\text{V}$  (1. Gen)

$+V_{GS} \text{ max} = +15\text{V}$  (2. Gen)



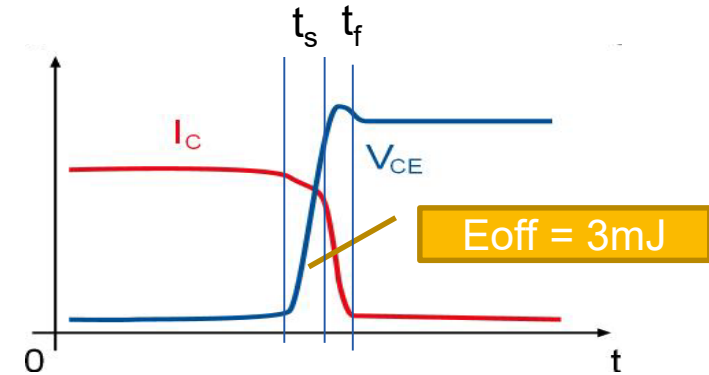
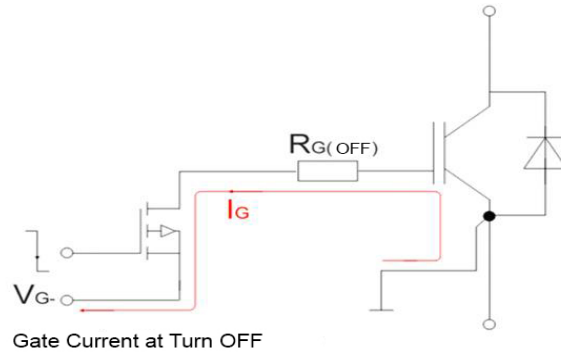
1. Gen



2. Gen

- $\approx 2\text{V}$  threshold voltage, but 15-20V needed to switch higher currents (fully enhanced)

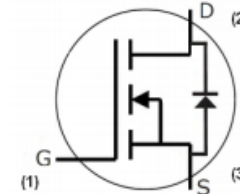
## Turn Off Gate Drive: SiC



- On and Off switching behaviour very similar (no tail current like IGBT)
- Switching speed mainly determined by  $R_{G(OFF)}$  gate resistor

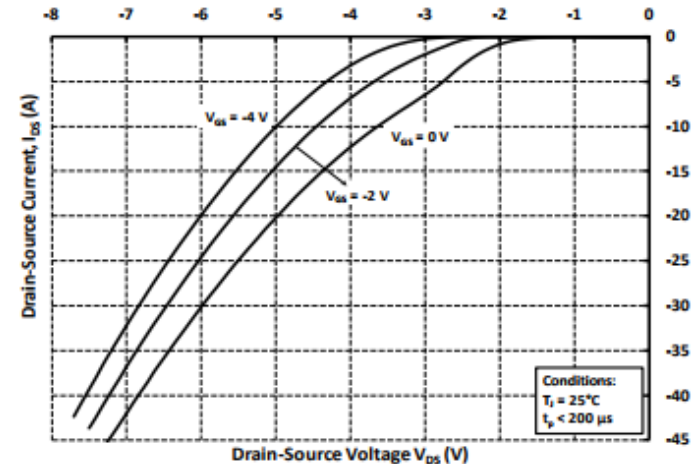
## -Ve Turn Off Gate Drive: SiC

$-V_{GS}$  abs. max = -10V (1. Gen)  
 or -4V (2. Gen)  
 (limited by the body diode characteristic)



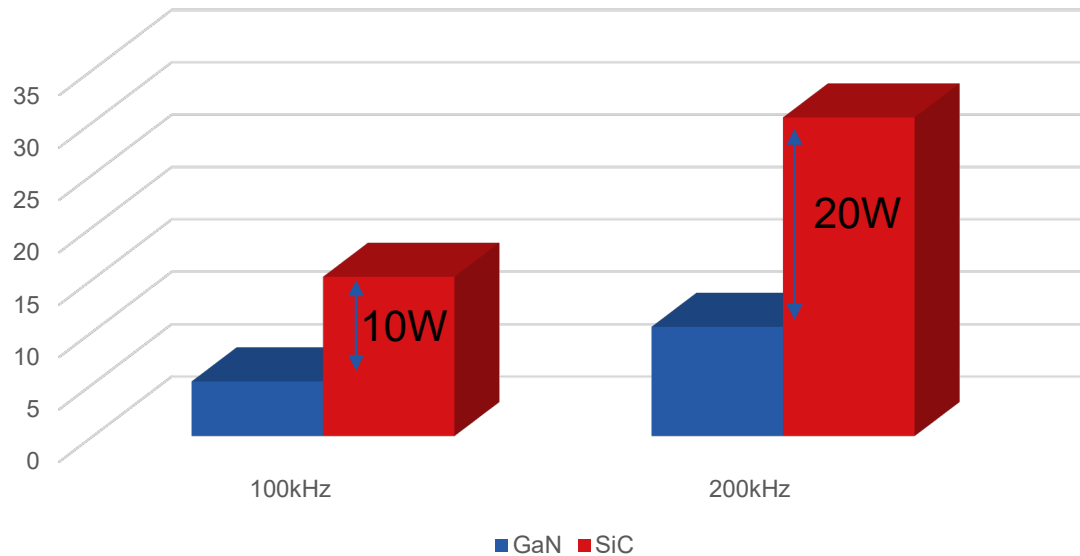
But operation at abs. max.  
 $-V_{GS}$  reduces the lifetime:

- 1. Gen: ideal  $-V_{GS} = -5V$
- 2. Gen: ideal  $-V_{GS} = -3V$

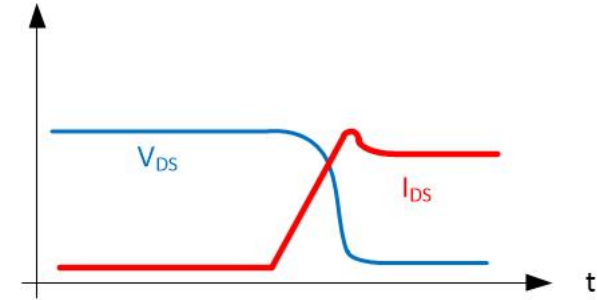
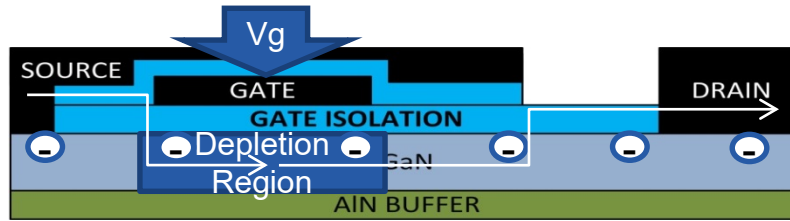


# GaN vs SiC-MOSFET

Switching Power Dissipation =  $E_{on} + E_{off}$  ) x  $f_{sw}$   
(-measured @ 400 V / 15 A

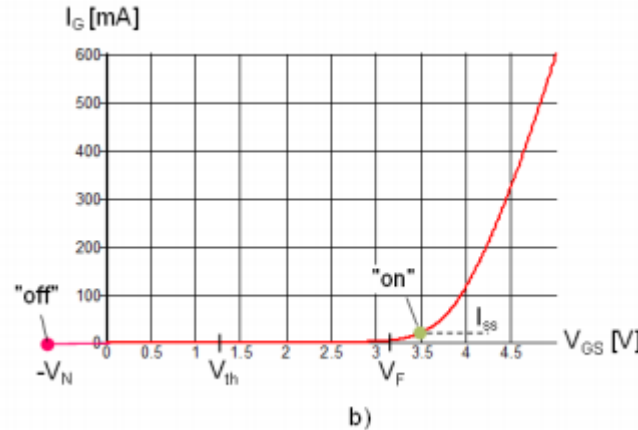
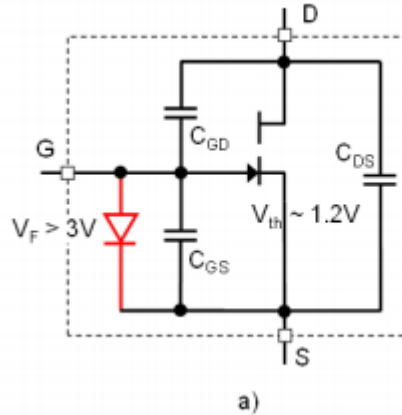


## Normally Off GaN E-HEMT



- Significantly lower switching dissipation than Si/SiC (electron injection)
- Inherently bidirectional (no body diode)
- Switching speed mainly determined by  $R_G$  gate resistor

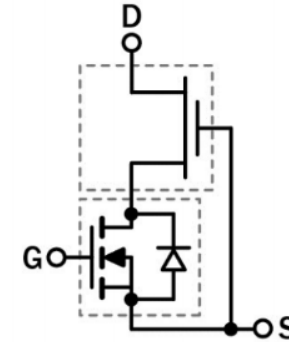
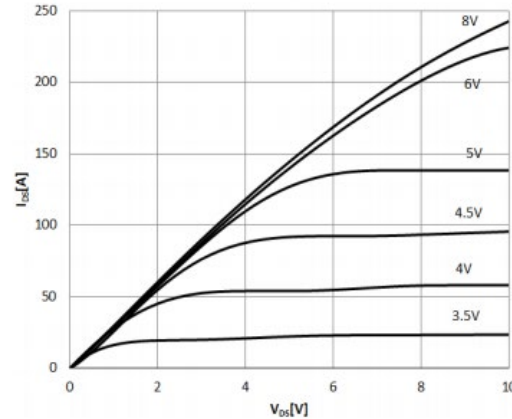
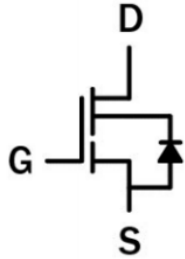
## Normally Off GaN E-HEMT



Source: GaN EiceDRIVER™ product family

- Stable  $V_{TH}$  (1.2V), but also low abs. max  $V_{GS} = 6V$
- Should be driven with single sided regulated 5V gate driver, or +5/-1V asymmetric gate drive for more gate drive security.





# GaN Cascode



- max  $V_{GS} = \pm 18V$ , but no advantage if driven with more than 8V
- Can be driven with single sided 9V gate driver, as a negative gate drive is not needed with the cascode configuration.

# Summary so far:

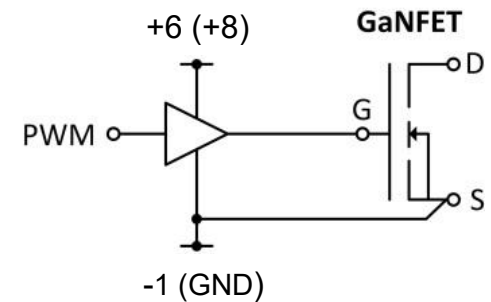
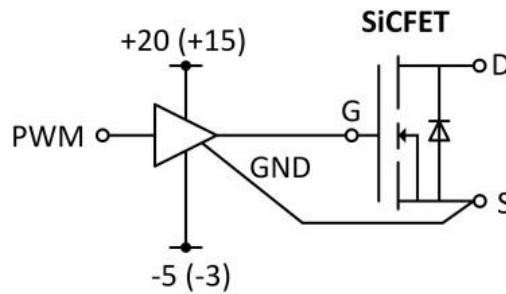
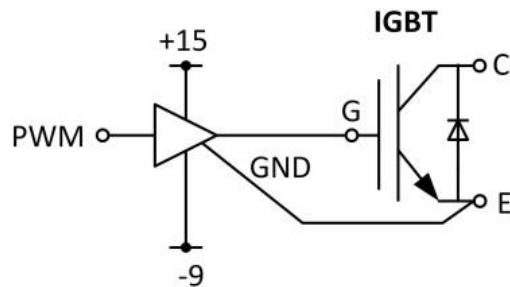
Need to eliminate the influence of parasitics when fast switching:

-  Reduce  $di/dt$  or  $dv/dt$  slew rates (drawback: causes higher losses)
-  Balance out  $L_{\text{Layout}}$  paths (may not be so easy in complex PCBs)
-  Use Kelvin contacts to eliminate the effect of ground bounce
-  Use negative gate drive (drawback: asymmetric floating supply required)

# Summary so far:

## Isolated gate drivers:

- 🔌 Use isolated gate drivers for both high side and low side.
- 🔌 Different floating output supply voltages are needed depending on type (IGBT, Si-MosFET, 1st./2nd.Gen SiC, E-HEMT GaN, Cascode-GaN)



# Reference Design R-Ref01-HB



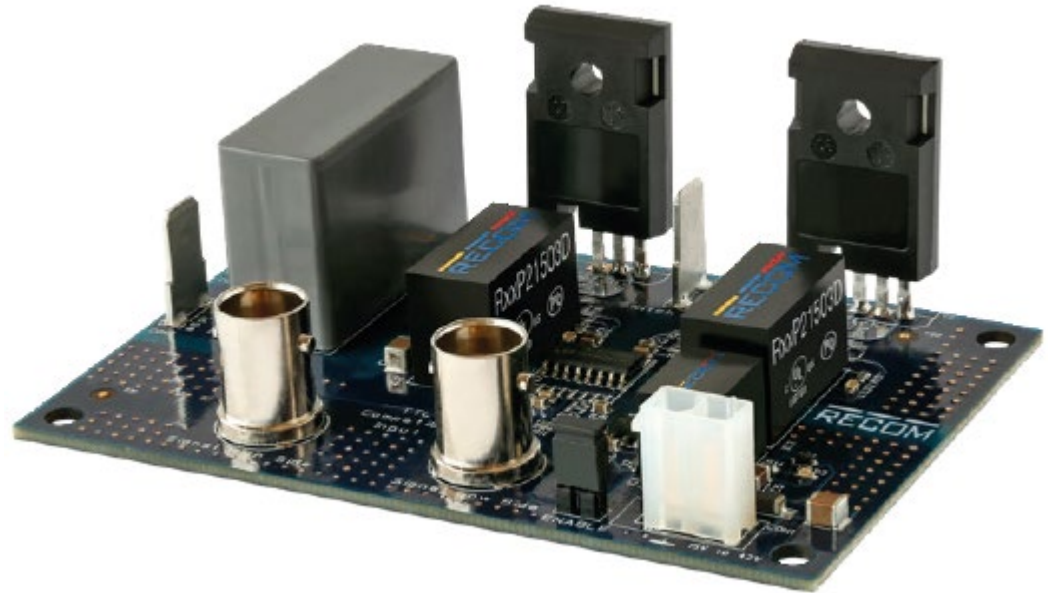
Half bridge reference design for  
fast switching (1000VDC)

Suitable for different gate drive  
voltages, e.g.

+6V, +15V/-3V, +15V/-9V,  
+20V/-5V .....

Suitable for TO-247 3-pin and  
4-pin transistors

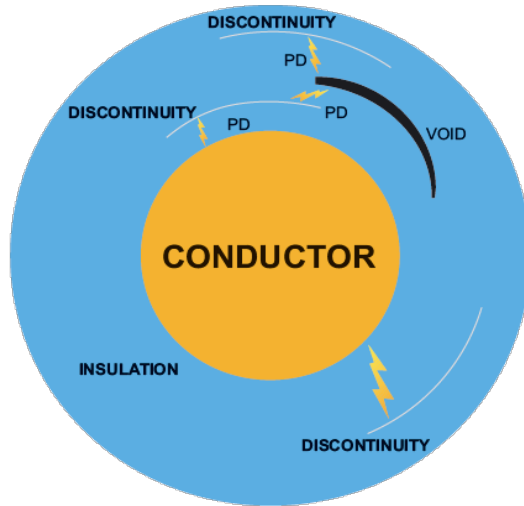
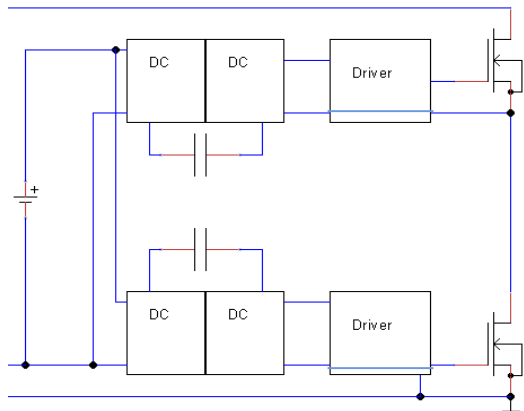
Available at Rutronik



# Choosing the Right DC/DC

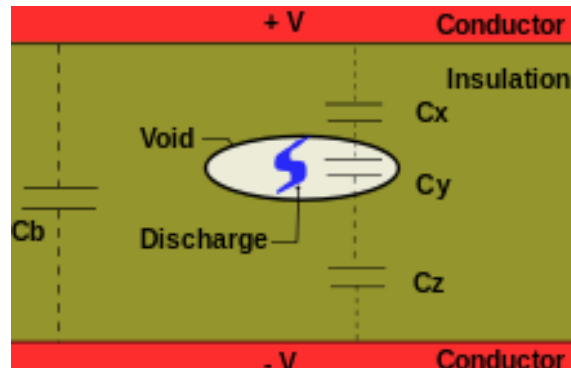
## Why is isolation capacitance so important?

- Partial Discharge



Source: Recom DC/DC Book of Knowledge

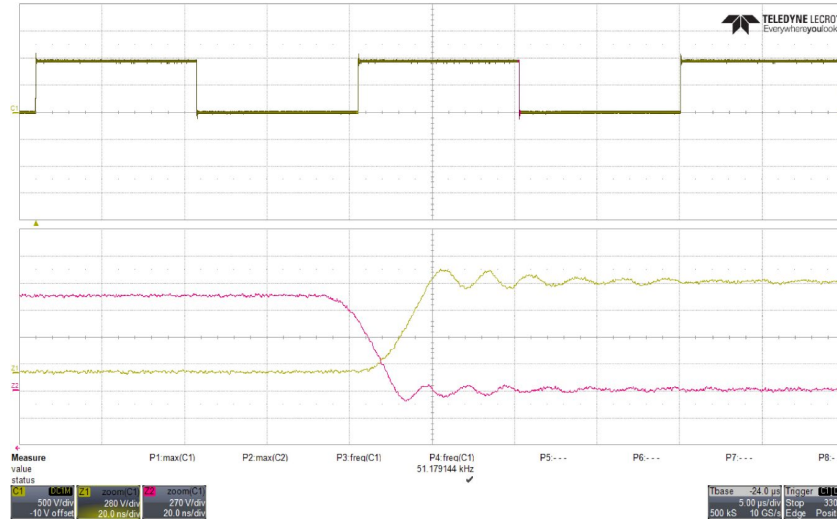
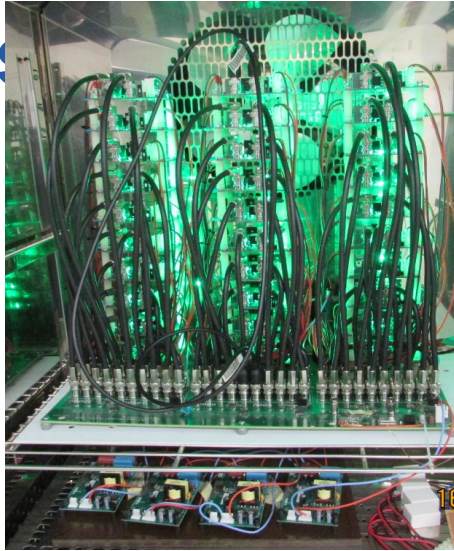
RECOM



Source: Wikipedia

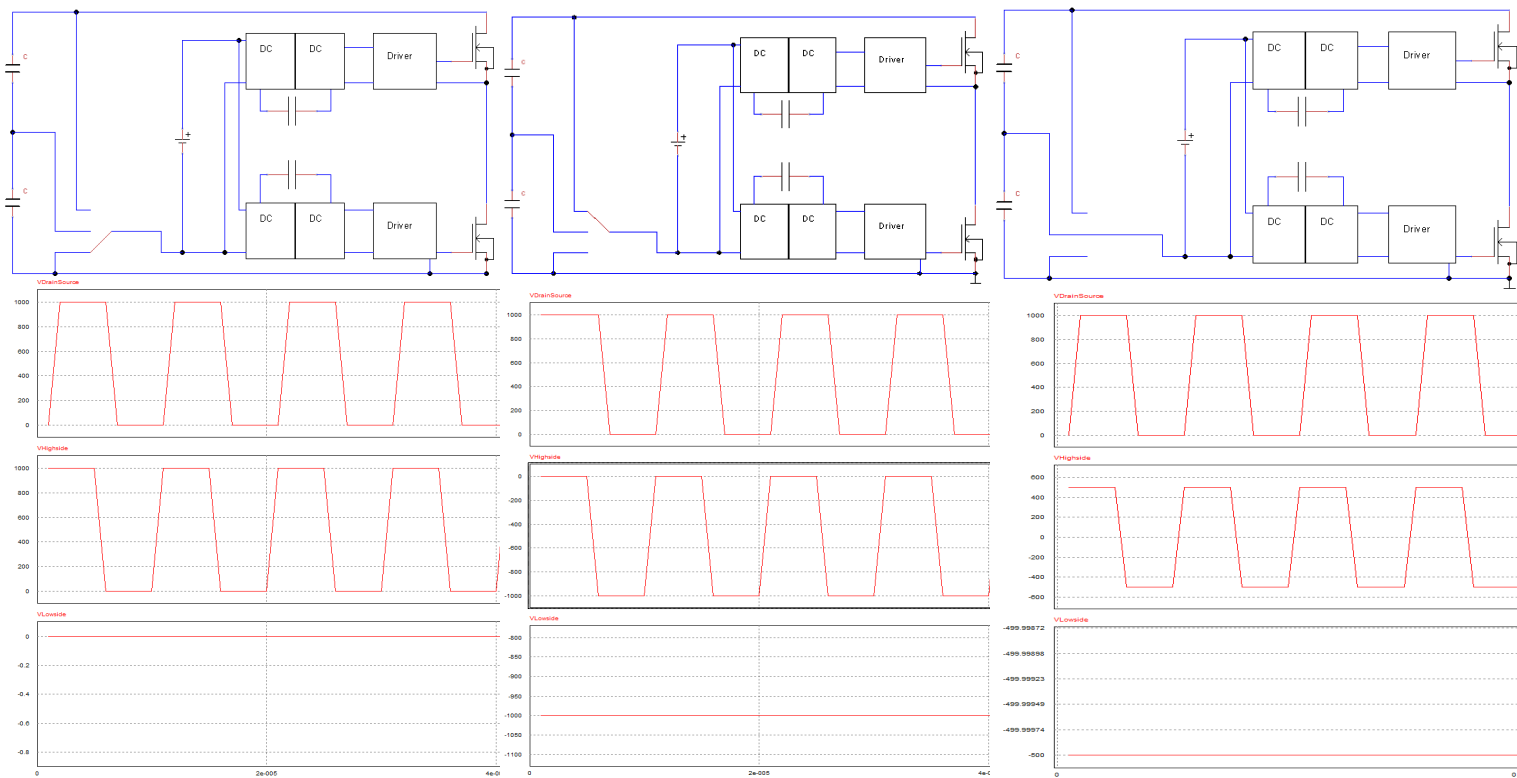
# Barrier Insulation Evaluation

Res



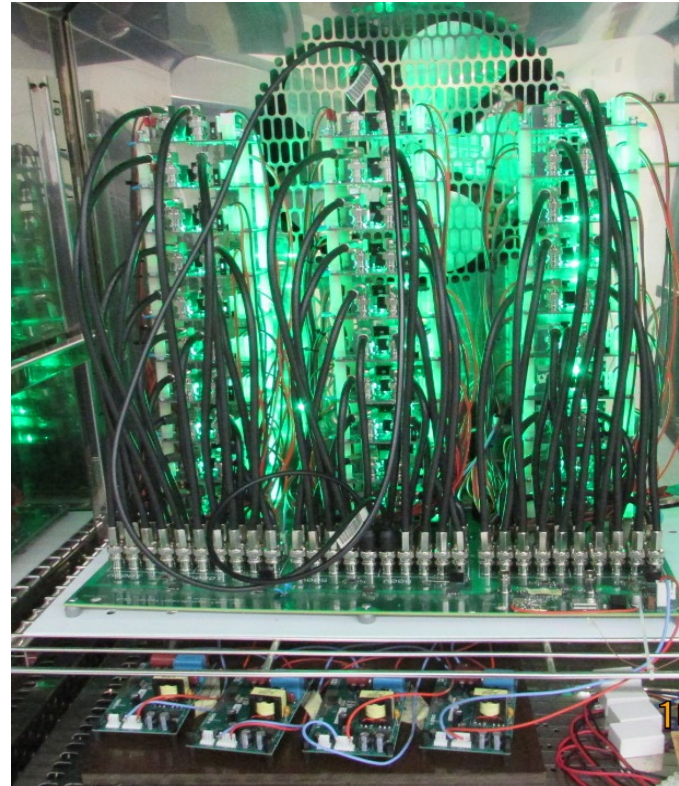
Recom R&D

Priv.-Doz. Dipl.-Ing. Dr. Techn. Christof Sumederer/TU Graz, FH Joanneum



## Test Parameters

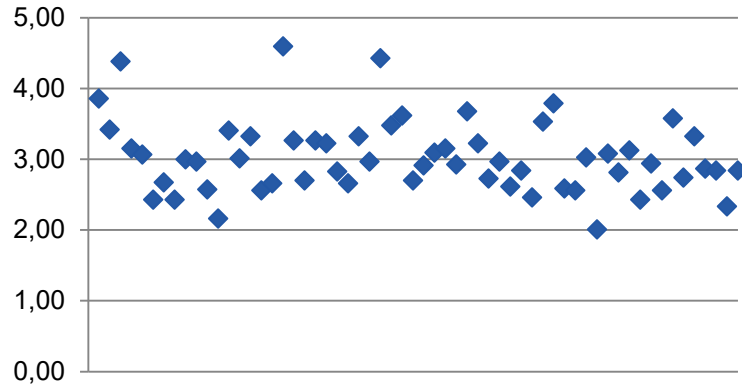
Test duration:	1464h
Test voltage:	1000V
Ambient temperature:	70°C
DC/DC converter Temp:	93°C
Transistor Temperature	116°C
Switching frequency	50kHz
dv/dt	65kV/ $\mu$ s



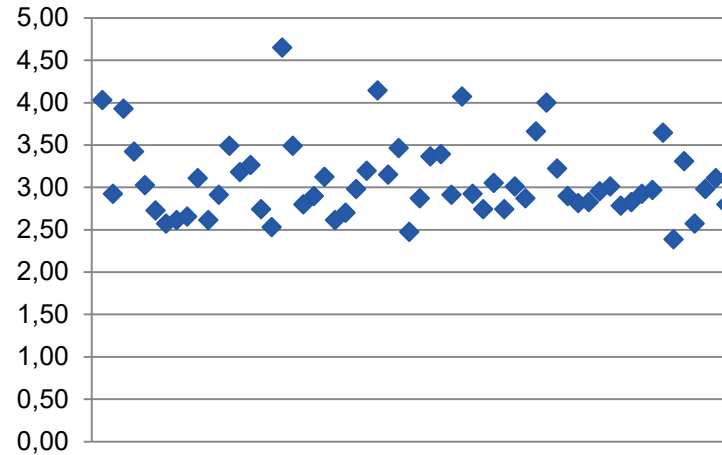
# BIER

## Partial discharge measurements

**VPD Peak [KV] before  
Test**



**VPD Peak [kV] after Test**



# Choosing the Right DC/DC



## Isolated SiC Gate Driver

$$P_{gate} = P_{driver} + (Q_{gate} f_{sw} \Delta V_{gate})$$

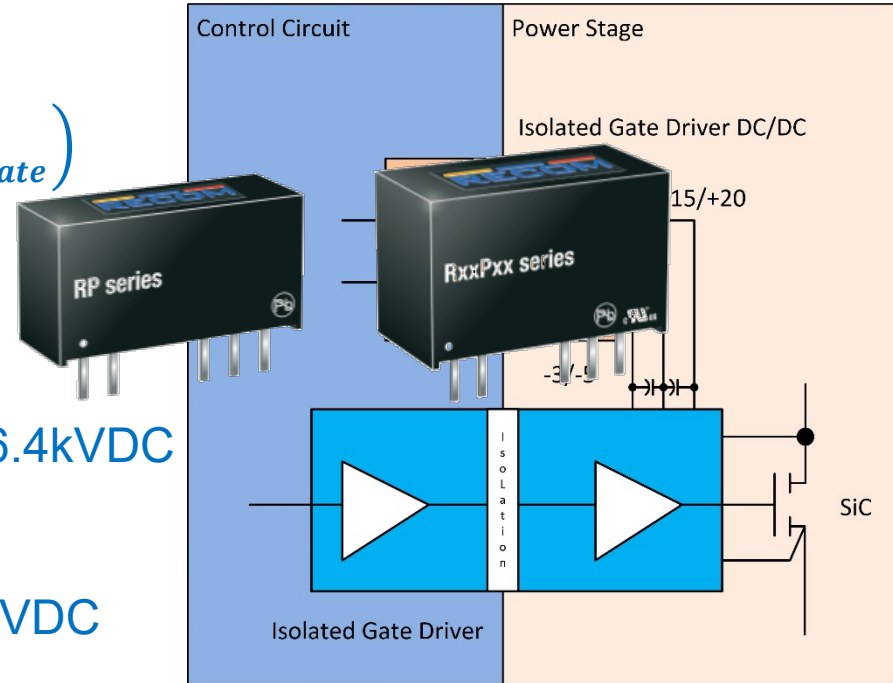
$$P_{gate} = 0.05 + 0.25 = 0.3W$$

(for 50kHz)

Dual Asymmetric output (unreg.)

e.g. **RxxP22005D** (2W, +20V/-5V, 6.4kVDC isolation, 3pF typ, SIP7)

or **RP-1509D** (1W, +15V/-9V, 5.2kVDC isolation, 4pF typ, SIP7)



# Choosing the Right DC/DC



## Isolated GaN Gate Driver

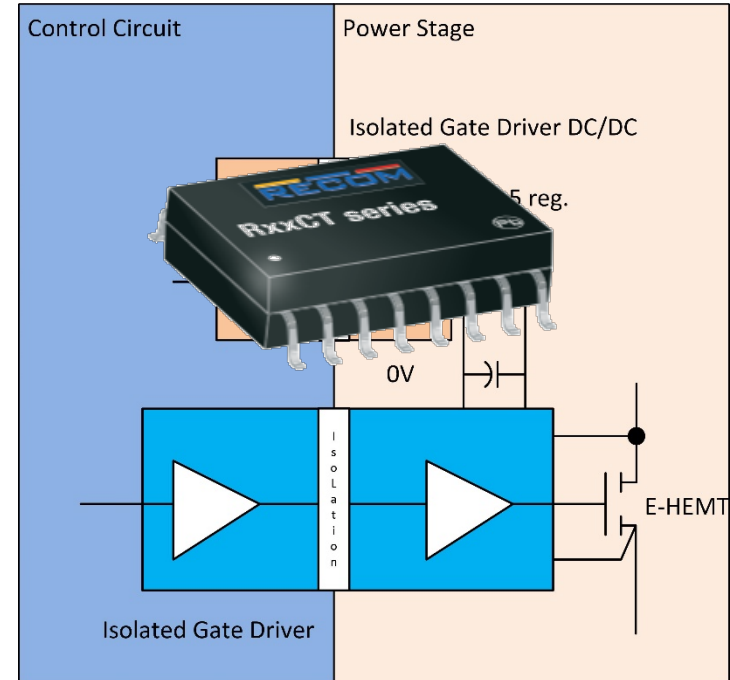
$$P_{gate} = P_{driver} + (Q_{gate} f_{sw} \Delta V_{gate})$$

$$P_{gate} = 0.05 + 0.05 = 0.1W$$

(for 500kHz)

## Single Regulated Output

e.g. **R05CT05** (0.4W, +5V reg.,  
5kVAC reinforced isolation, 3.5pF typ,  
SOIC-16 SMD)



# Choosing the Right DC/DC



**R05CT05S**

Elektronik  
Magazine's  
*Product of  
the Year  
2021  
Silver Award.*



# Choosing the Right DC/DC

## Isolated E-HEMT GaN Gate Driver

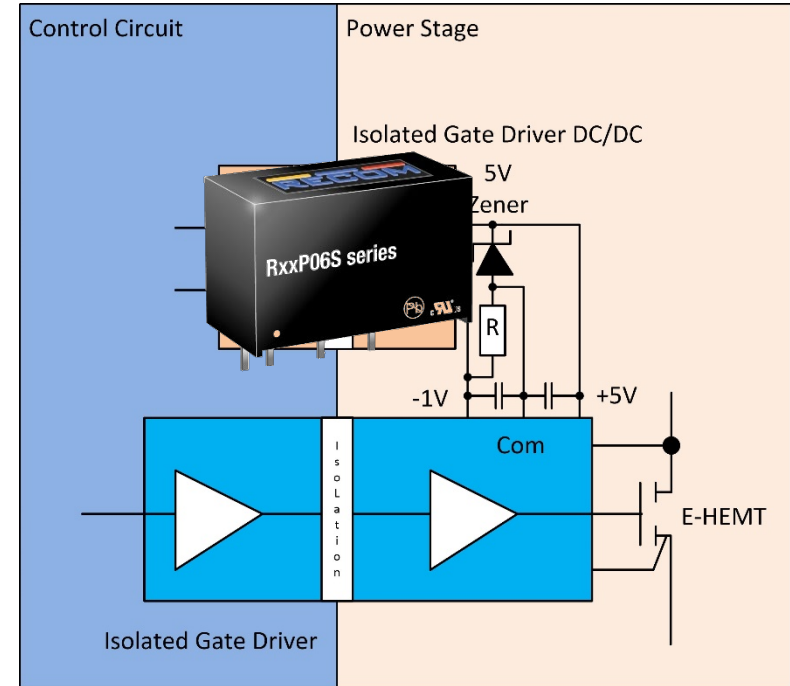
$$P_{gate} = P_{driver} + (Q_{gate} f_{sw} \Delta V_{gate})$$

$$P_{gate} = 0.05 + 0.05 = 0.1W$$

(for 500kHz)

Dual Asymmetric Output (partly regulated)

e.g. **RxxP06S** (1W, +6V, 6.4kVDC isolation, 4pF typ, SIP7)



# Choosing the Right DC/DC



## Isolated Cascode GaN Gate Driver

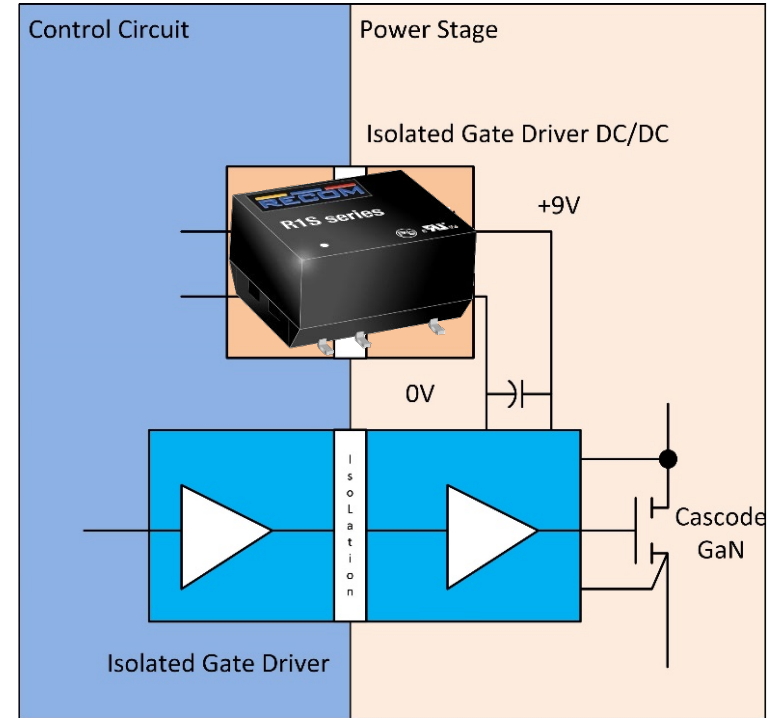
$$P_{gate} = P_{driver} + (Q_{gate} f_{sw} \Delta V_{gate})$$

$$P_{gate} = 0.05 + 0.05 = 0.1W$$

(for 500kHz)

Single Unregulated Output

e.g. **R1S-0509** (1W, +9V,  
3kVDC isolation, 15pF typ,  
8pin SMD)



# Choosing the Right DC/DC

„Solid State Transformer“ e.g. stacked  
3.3kV/800A SiC power modules

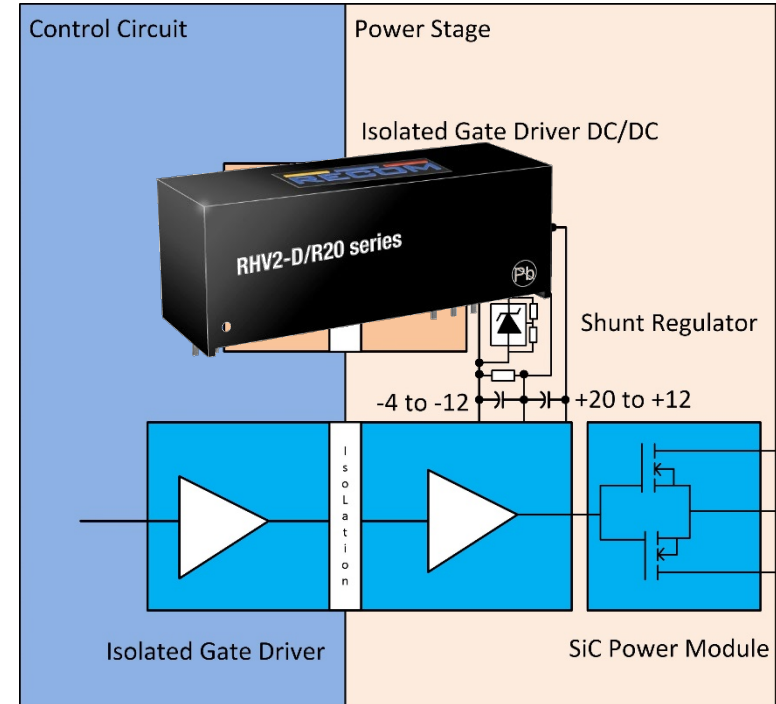
$$P_{gate} = P_{driver+reg} + (Q_{gate} f_{sw} \Delta V_{gate})$$

$$P_{gate} = 1.0 + 0.67 = 1.7W$$

(for 10kHz)

Single Semi-regulated Output

e.g. **RHV2-2424S/R20** (2W, +24V,  
**20kVDC** isolation, 3.5pF typ, SIP16)



# Choosing the Right DC/DC

## Paralleled Transistor SiC Gate Driver

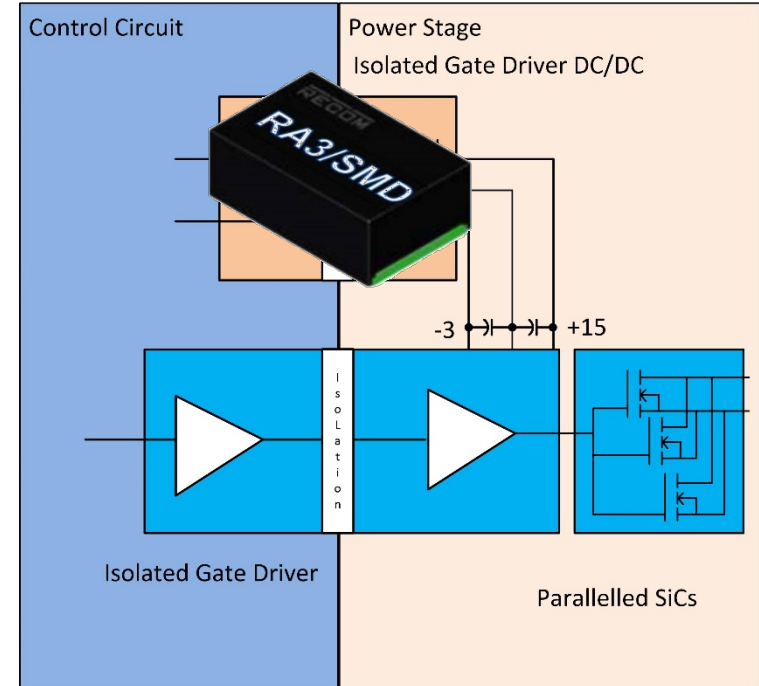
$$P_{gate} = P_{driver} + n \left( Q_{gate} f_{sw} \Delta V_{gate} \right)$$

$$P_{gate} = 0.6 + 3 \times 0.5 = 2.1W$$

(for 100kHz)




## Dual Asymmetrical Outputs

e.g. **RA3-051503D** (3W, +15/-3V,  
5.2kVDC isolation, <10pF, Pinless SMD  
(to be released soon))



# High Isolated DC/DC Converters for Gate Drivers



 <b>IGBT</b>	 <b>SiC</b>	 <b>GaN</b>
RxxP2xx, RxxPxx, RP, RH & RKZ series in a compact SIP7 case. RV & RGZ series in DIP14 and DIP24	RxxP21503D, RxxP22005D, RKZ-xx2005D, and RA3 series in compact SIP7 or DIP16 cases	RxxCTxx, RxxPxx, RxxP2xx, RK, RP and RA3 in compact SMD, SIP8 or SIP7 cases
+15V and -9V outputs	+15/-3V and +20/-5V outputs	+5V, +6V, +8, +9V, and +7/-1V outputs
1W or 2W total outputs	2W or 3W total output	1W, 2W, or 3W output power
5V, 12V or 24V inputs	5V, 12V, 15V or 24V inputs	5V, 12V, 15V, or 24V inputs
Up to 86% efficiency	Up to 87% efficiency	Up to 83% efficiency
Symmetric power	Symmetric power or symmetric current output	
Up to 6.4kVDC isolation		
Up to +90°C operating temperature		
EN certified		

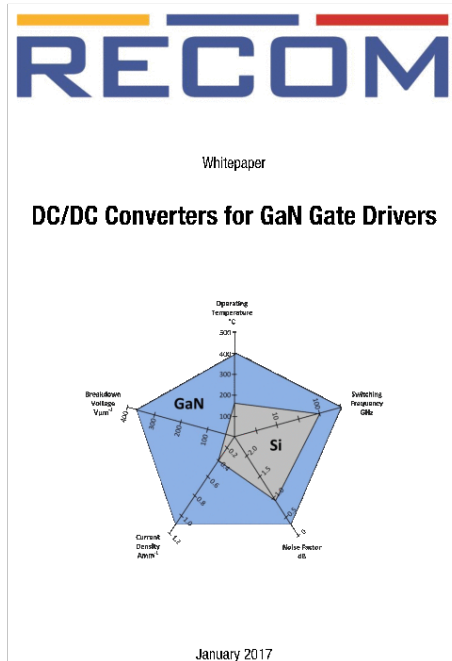
[www.recom-power.com/gate-drivers](http://www.recom-power.com/gate-drivers)

# Summary



- The voltage on the insulation can be significantly higher than the bus voltage
- High switching speed has an influence on insulation characteristics, so choose high isolation with low isolation capacitance
- Isolation test voltages are often based on low frequencies and may not be representative of true performance.
- Partial discharge measurement gives more information about the insulation than high pot testing
- BIER Test proves : RECOM DC-DC power supplies are suitable for long term high  $dv/dt$  without suffering from isolation deterioration.

# Website Resources



**WE POWER YOUR PRODUCTS**  
MODULES FOR DISTRIBUTED POWER ARCHITECTURE

